

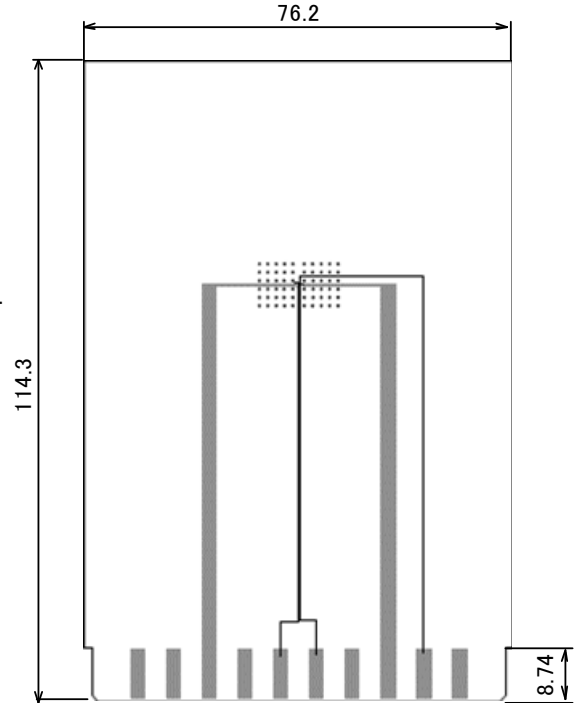
● **WLP-5-08 Power Dissipation (JESD51-7)**

Power dissipation data for the WLP-5-08 is shown in this page.  
 The value of power dissipation varies with the mount board conditions.  
 Please use this data as one of reference data taken in the described condition.

**1. Measurement Condition (Reference data)**

- Condition : Mount on a board
- Ambient : Natural convection
- Soldering : Lead (Pb) free
- Board : The board using 4 copper layer.  
 (76.2mm × 114.3mm ••• Area: about 8700mm<sup>2</sup>)
- 1st layer※ : No copper foil (Signal layer)
- 2nd layer : 70mm × 70mm\_Connected to heat-sink.
- 3rd layer : 70mm × 70mm\_Connected to heat-sink.
- 4th layer : No copper foil (Signal layer)
- Material : Glass Epoxy(FR-4)
- Thickness : 1.6mm
- Through-hole  $\phi$  0.2mm x 60pcs

※The copper layer thickness is 35  $\mu$  m, caused by signal layer pattern.



**2. Power Dissipation vs. Ambient temperature**

Board Mount(Tjmax = 125°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)	$\theta_{ja}$ (°C/W)
25	500	200.00
105	100	

